

IRS21844MPBF HALF-BRIDGE DRIVER

Features

- Floating channel designed for bootstrap operation
- Fully operational to + 600 V
- Tolerant to negative transient voltage, dV/dt immune
- Gate drive supply range from 10 V to 20 V
- Undervoltage lockout for both channels
- 3.3 V and 5 V input logic compatible
- Matched propagation delay for both channels
- Logic and power ground +/- 5 V offset
- Lower di/dt gate driver for better noise immunity
- Output source/sink current capability 1.4 A/1.8 A
- Lead free, RoHS compliant

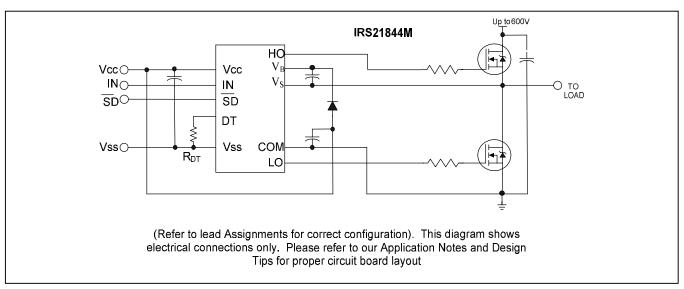
Product Summary

Topology	Half-Bridge			
Voffset	600 V			
Vout	10 V – 20 V			
I _{o+} & I _{o-} (typical)	1.9 A & 2.3 A			
ton & toff (typical)	680 ns & 270 ns			
Deadtime (typical)	400 ns (R _{DT} = 0 Ω)			
	5 μs (R_{DT} = 200 k Ω)			

Package Options



Typical Connection



Description

The IRS21844MPBF is a high voltage, high speed power MOSFET and IGBT drivers with dependent high and low-side referenced output channels. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. The logic input is compatible with standard CMOS or LSTTL output, down to 3.3 V logic. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high-side configuration which operates up to 600 V.

Feature Comparison: IRS2181(4)/IRS2183(4)/IRS2184(4)

Part	Input Logic	Cross- Conduction Prevention logic	Dead-Time	Ground Pins	Ton/Toff
2181				COM	100/000 po
21814	HIN/LIN	no	none	Vss/COM	180/220 ns
2183			Internal 500ns	COM	100/000 po
21834	HIN/LIN	yes	Programmable 0.4 – 5 us	Vss/COM	180/220 ns
2184			Internal 500ns	COM	690/070 pg
21844	IN/SD	yes	Programmable 0.4 – 5 us	V _{SS} /COM	680/270 ns

Qualification Information[†]

<u>cuannication informatio</u>	111					
		Industrial ^{††} (per JEDEC JESD 47)				
0			,			
Qualification Level			as passed JEDEC's Industrial			
		qualification. IR's C	onsumer qualification level is			
		granted by extension of	f the higher Industrial level.			
Majatura Canaitivitu	Laval	MI DO 4 4 4 4	MSL2 ^{†††}			
Moisture Sensitivity Level		MLPQ4x4 14L	(per IPC/JEDEC J-STD-020)			
	Machine Madel		Class A (+/-100V)			
	Machine Model	(per JEDEC standard JESD22-A115)				
ESD	Lluman Dady Madel	Class 1C (+/-1500V)				
ESD	Human Body Model	(per EIA/JEDEC standard EIA/JÉSD22-A114)				
	Charged Davies Medal	Class III (+/-1000V)				
Charged Device Model		(per JEDEC standard JESD22-C101)				
IC Latabilia Toot		Class II, Level A				
IC Latch-Up Test		(per JESD78A)				
RoHS Compliant			Yes			

- † Qualification standards can be found at International Rectifier's web site http://www.irf.com/
- †† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information.
- ††† Higher MSL ratings may be available for the specific package types listed here. Please contact your International Rectifier sales representative for further information.



Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min	Max	Units
V_{B}	High-side floating absolute voltage	-0.3	620	
Vs	High-side floating supply offset voltage	V _B - 25	$V_B + 0.3$	
V_{HO}	High-side floating output voltage	V _S - 0.3	$V_B + 0.3$	
Vcc	Low-side and logic fixed supply voltage	-0.3	20 [†]	V
V_{LO}	Low-side output voltage	-0.3	$V_{CC} + 0.3$	V
DT	Programmable deadtime pin voltage		$V_{CC} + 0.3$	
V _{IN}	Logic input voltage (IN & SD)	Vss -0.3	V _{CC} + 0.3	
Vss	Logic ground	V _{CC} - 20	Vcc + 0.3	
dVs/dt	Allowable offset supply voltage transient	_	50	V/ns
P _D	Package power dissipation @ TA ≤ 25°C	_	2.08	W
Rth _{JA}	Thermal resistance, junction to ambient	_	36	°C/W
TJ	Junction temperature	_	150	
Ts	Storage temperature	-50	150	°C
TL	Lead temperature (soldering, 10 seconds)	_	300	

[†] All supplies are fully tested at 25 V and an internal 20 V clamp exists for each supply.

Recommended Operating Conditions

The input/output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions. The $V_{\rm S}$ and $V_{\rm SS}$ offset rating are tested with all supplies biased at a 15 V differential.

Symbol	Definition	Min	Max	Units
V _B	High-side floating supply absolute voltage	Vs + 10	Vs + 20	
Vs	High-side floating supply offset voltage	(††)	600	
V_{HO}	High-side floating output voltage	Vs	V _B	
Vcc	Low-side and logic fixed supply voltage	10	20	V
V_{LO}	Low-side output voltage	0	Vcc	V
V_{IN}	Logic input voltage (IN & SD) (†††)	Vss	Vcc	
DT	Programmable deadtime pin voltage	Vss	Vcc	
Vss	Logic ground	-5	5	
T _A	Ambient temperature	-40	125	°C

^{††} Logic operational for V_S of -5 V to +600 V. Logic state held for V_S of -5 V to $-V_{BS}$. (Please refer to Design Tip DT97-3 for more details).

^{†††} HIN and LIN are internally clamped with a 5.2 V zener diode.



Dynamic Electrical Characteristics

VBIAS (VCC, VBS) = 15 V, VSS = COM, CL = 1000 pF, TA = 25°C, DT = VSS unless otherwise specified.

Symbol	Definition	Min	Тур	Max	Units	Test Conditions
ton	Turn-on propagation delay	_	680	900		$V_S = 0 V$
toff	Turn-off propagation delay	_	270	400		Vs = 0 V or 600 V
t _{sd}	Shut-down propagation delay	_	180	270		
MTon	Delay matching, HS & LS turn-on		0	90		
MT _{off}	Delay matching , HS & LS turn-off	_	0	40	ns	
tr	Turn-on rise time		40	60		V 0.V
t _f	Turn-off fall time	_	20	35		Vs = 0 V
DT	Deadtime: LO turn-off to HO turn-on (DT _{LO-HO}) &		400	520		$R_{DT} = 0 \Omega$
DT	HO turn-off to LO turn-on (DT _{HO-LO})	4	5	6	μs	R_{DT} = 200 k Ω
MDT	Deadtime matching DT _{LO-HO} - DT _{HO-LO}		0	50	200	$R_{DT} = 0 \Omega$
MDT			0	600	ns	R_{DT} = 200 k Ω

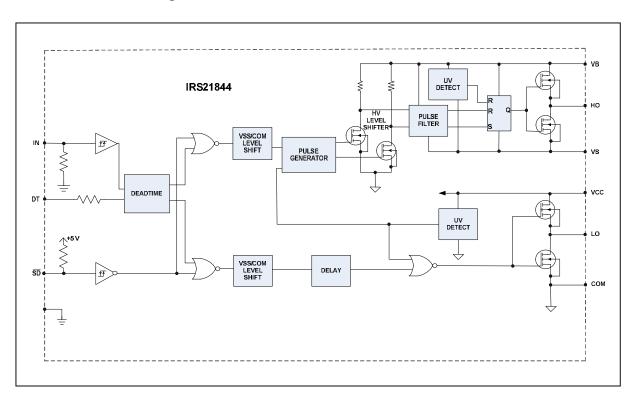
Static Electrical Characteristics

 V_{BIAS} (V_{CC} , V_{BS}) = 15 V, V_{SS} = COM, DT = V_{SS} and T_A = 25°C unless otherwise specified. The V_{IL} , V_{IH} and I_{IN} parameters are referenced to V_{SS} /COM and are applicable to the respective input leads: IN and \overline{SD} . The V_{O} , I_{O} and R_{OD} parameters are referenced to COM and are applicable to the respective output leads: HO and LO.

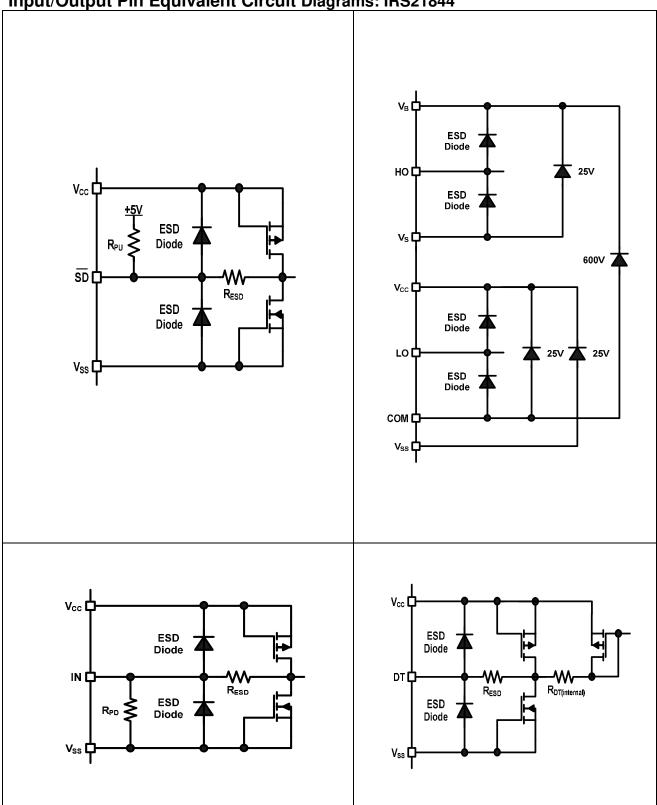
Symbol	Definition	Min	Тур	Max	Units	Test Conditions
V_{IH}	Logic "1" input voltage for HO & logic "0" for LO	2.5	_	_		
V_{IL}	Logic "0" input voltage for HO & logic "1" for LO		_	0.8		V _{CC} = 10 V to 20 V
$V_{\text{SD,TH+}}$	SD input positive going threshold	2.5	_	_	V	VCC = 10 V 10 20 V
$V_{\text{SD,TH-}}$	SD input negative going threshold - 0.8		v			
V_{OH}	High level output voltage, V_{BIAS} - V_{O}	_	_	1.4		$I_O = 0 A$
V_{OL}	Low level output voltage, Vo		_	0.2		$I_O = 20 \text{ mA}$
I _{LK}	Offset supply leakage current		_	50		$V_B = V_S = 600 \text{ V}$
I _{QBS}	Quiescent V _{BS} supply current	20	60	150	μΑ	V _{IN} = 0 V or 5 V
I _{QCC}	Quiescent V _{CC} supply current	0.4	1.0	1.6	mA	VIN = U V OI 5 V
$I_{\text{IN+}}$	Logic "1" input bias current — 25 60			$IN = 5 V, \overline{SD} = 0 V$		
I _{IN-}	Logic "0" input bias current		_	5.0	μΑ	$IN = 0 V, \overline{SD} = 5 V$
V _{CCUV+} V _{BSUV+}	V_{CC} and V_{BS} supply undervoltage positive going threshold	8.0	8.9	9.8		
V _{CCUV-} V _{BSUV-}	V_{CC} and V_{BS} supply undervoltage negative going threshold	7.4	8.2	9.0	٧	
Vccuvh Vbsuvh	Hysteresis	0.3	0.7	_		
I _{O+}	Output high short circuit pulsed current	1.4	1.9		Α	$V_O = 0 V$, PW $\leq 10 \mu s$
I _{O-}	Output low short circuit pulsed current	1.8	2.3	_	A	$V_0 = 15 \text{ V},$ PW \le 10 \mus



Functional Block Diagram: IRS21844



Input/Output Pin Equivalent Circuit Diagrams: IRS21844

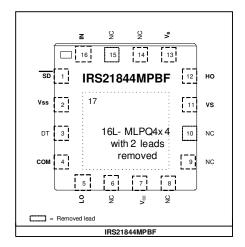




Lead Definitions

PIN	Symbol	Description
1	SD	Logic input for shutdown (referenced to V _{SS})
2	V_{SS}	Logic ground
3	DT	Programmable deadtime lead, referenced to Vss
4	COM	Low-side return
5	LO	Low-side gate drive output
6	NC	No Connection
7	Vcc	Low-side and logic fixed supply
8	NC	No Connection
9	NC	No Connection
10	NC	No Connection (removed lead)
11	Vs	High-side floating supply return
12	НО	High-side gate drive output
13	V_{B}	High-side floating supply
14	NC	No Connection
15	NC	No Connection (removed lead)
16	IN	Logic input for high-side gate driver output (HO), in phase

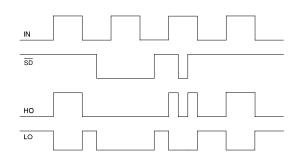
Lead Assignments: IRS21844



Central exposed pad (17) is internally connected to ground. It is recommended to connect the central exposed pad to COM externally for better electrical performance.



Application Information and Additional Details



IN (LO)

50%

50%

t_{on}

t_r

90%

10%

Figure 1: Input/Output Timing Diagram

Figure 2: Switching Time Waveform Definitions

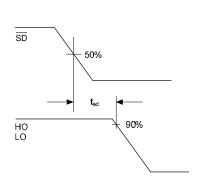


Figure 3: Shutdown Waveform Definitions

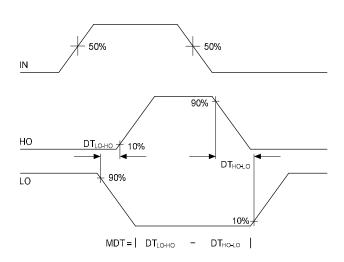


Figure 4: Deadtime Waveform Definitions

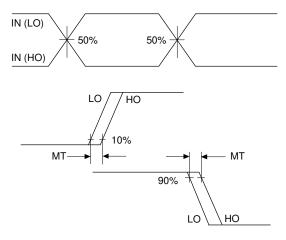


Figure 5: Delay Matching Waveform Definitions

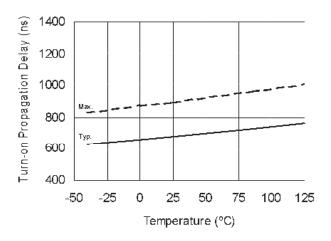


Figure 6A. Turn-On Propagation Delay vs. Temperature

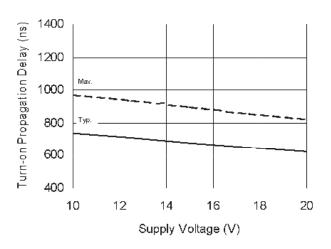


Figure 6B. Turn-On Propagation Delay vs. Supply Voltage

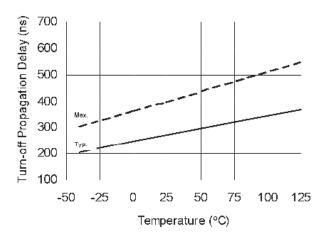


Figure 7A. Turn-Off Propagation Delay vs. Temperature

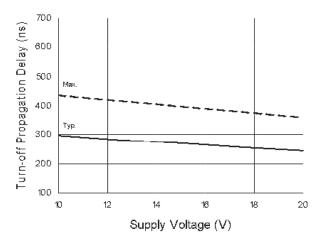


Figure 7B. Turn-Off Propagation Delay vs. Supply Voltage

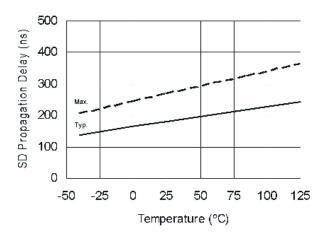


Figure 8A. SD Propagation Delay vs. Temperature

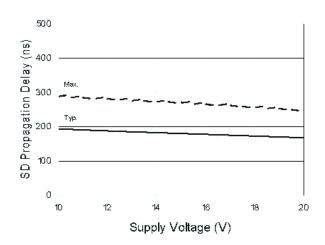


Figure 8B. SD Propagation Delay vs. Supply Voltage

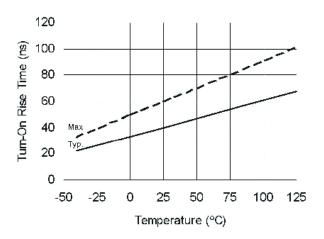


Figure 9A. Turn-On Rise Time vs.
Temperature

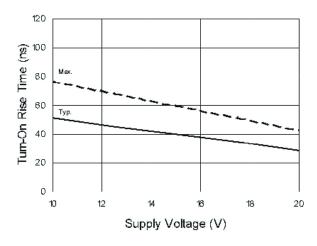


Figure 9B. Turn-On Rise Time vs. Supply Voltage

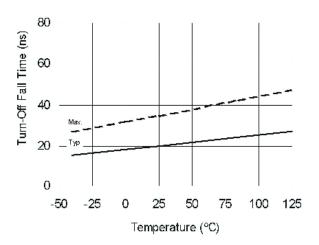


Figure 10A. Turn-Off Fall Time vs. Temperature

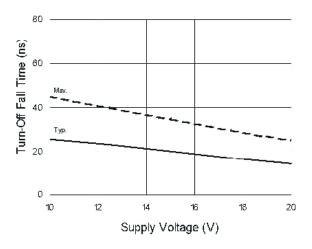


Figure 10B. Turn-Off Fall Time vs. Supply Voltage

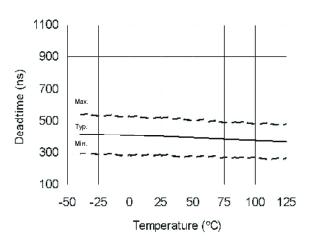


Figure 11A. Deadtime vs. Temperature

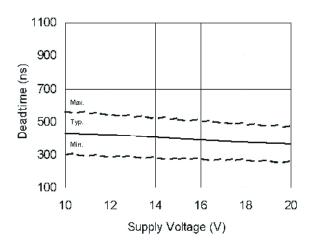


Figure 11B. Deadtime vs. Supply Voltage

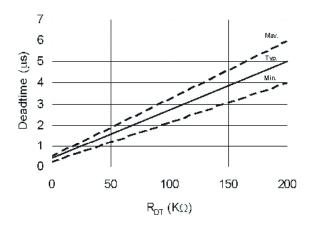


Figure 11C. Deadtime vs. $R_{\rm DT}$

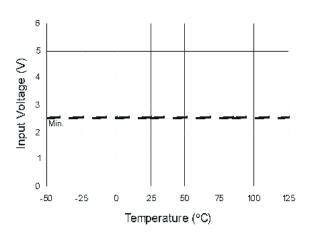


Figure 12A. Logic "1" Input Voltage vs. Temperature

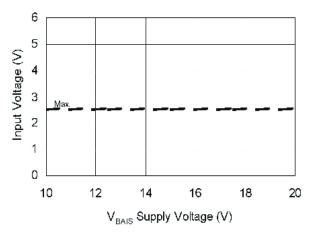


Figure 12B. Logic "1" Input Voltage vs. Supply Voltage

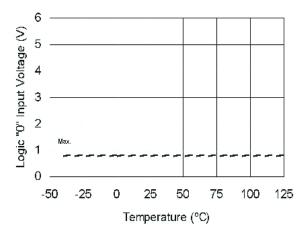


Figure 13A. Logic "0" Input Voltage vs. Temperature

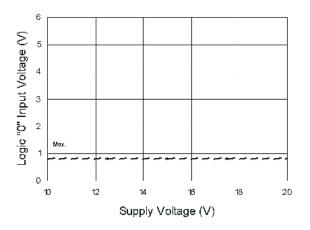


Figure 13B. Logic "0" Input Voltage vs. Supply Voltage

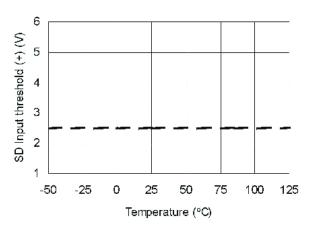


Figure 14A. SD input positive going threshold (+) vs. Temperature

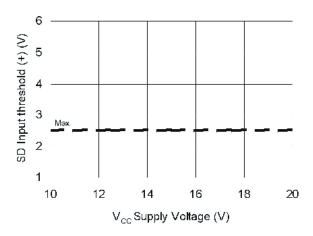


Figure 14B. SD input positive going threshold (+) vs. Supply Voltage

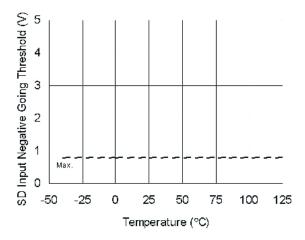


Figure 15A. SD Input Negative Going Threshold vs. Temperature

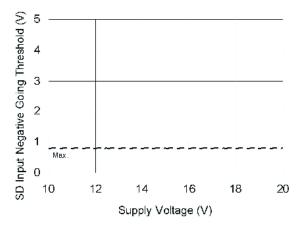


Figure 15B. SD Input Negative Going Threshold vs. Supply Voltage

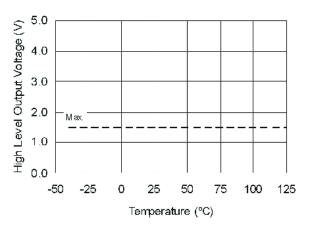


Figure 16A. High Level Output Voltage vs. Temperature (I_O = 0 mA)

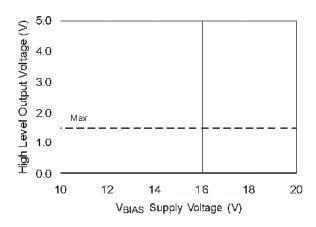


Figure 16B. High Level Output Voltage vs. Supply Voltage (Io = 0 mA)

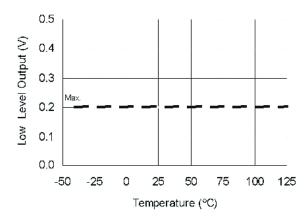


Figure 17A. Low Level Output vs. Temperature

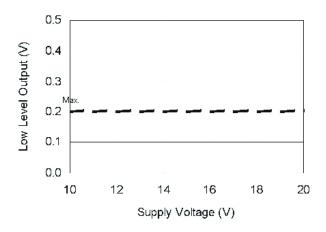


Figure 17B. Low Level Output vs. Supply Voltage

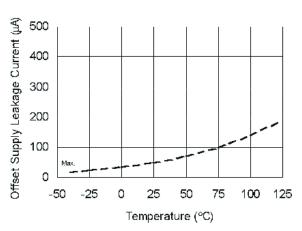


Figure 18A. Offset Supply Leakage Current vs. Temperature

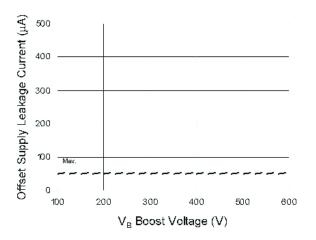


Figure 18B. Offset Supply Leakage Current vs. $V_{\rm B}$ Boost Voltage

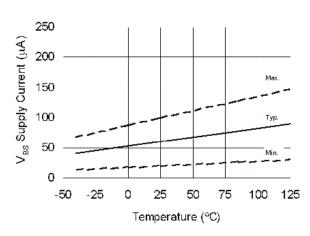


Figure 19A. V_{BS} Supply Current vs. Temperature

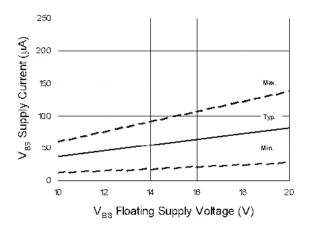


Figure 19B. V_{BS} Supply Current vs. V_{BS} Floating Supply Voltage

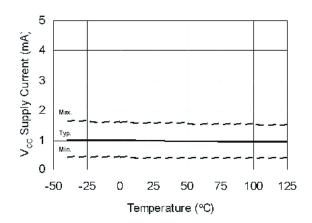


Figure 20A. V_{cc} Supply Current vs. Temperature

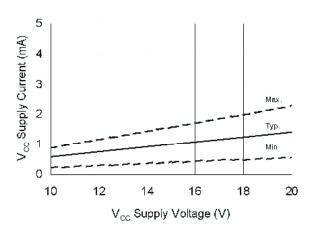


Figure 20B. $V_{\rm cc}$ Supply Current vs. $V_{\rm cc}$ Supply Voltage

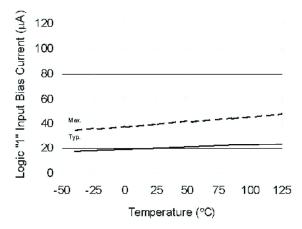


Figure 21A. Logic "1" Input Bias Current vs. Temperature

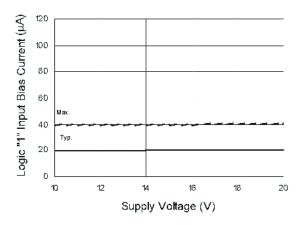


Figure 21B. Logic "1" Input Bias Current vs. Supply Voltage

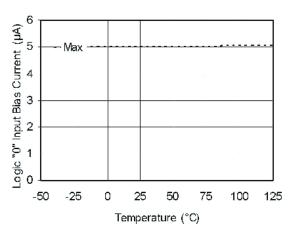


Figure 22A. Logic "0" Input Bias Curremt vs. Temperature

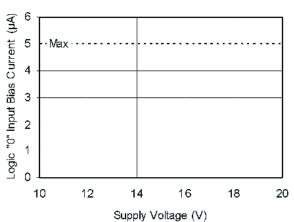


Figure 22B. Logic "0" Input Bias Curremt vs. Voltage

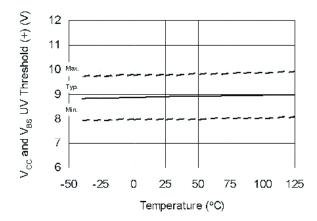


Figure 23. V_{cc} and V_{BS} Undervoltage Threshold (+) vs. Temperature

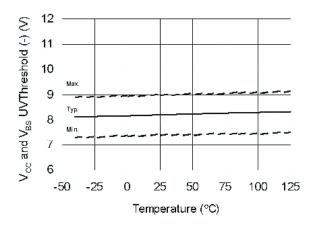


Figure 24. $\rm V_{CC}$ and $\rm V_{BS}$ Undervoltage Threshold (-) vs. Temperature

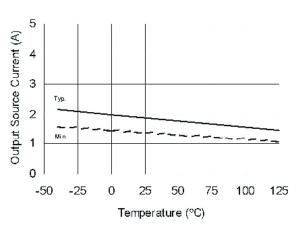


Figure 25A. Output Source Current vs. Temperature

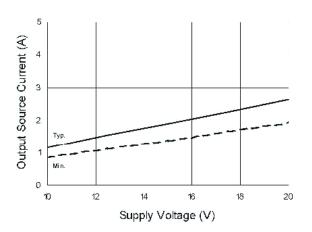


Figure 25B. Output Source Current vs. Supply Voltage

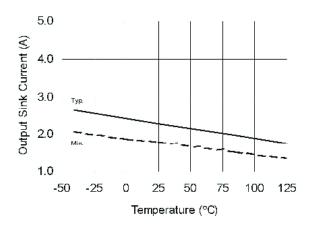


Figure 26A. Output Sink Current vs. Temperature

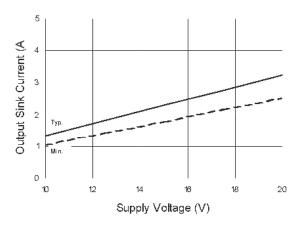


Figure 26B. Output Sink Current vs. Supply Voltage

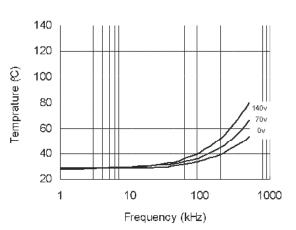


Figure 27. IRS2181 vs. Frequency (IRFBC20), $\rm R_{gate} = 33~\Omega,~V_{CC} = 15~V$

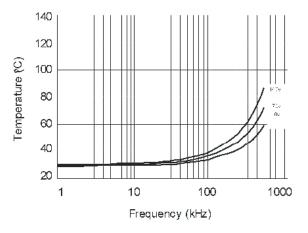


Figure 28. IRS2181 vs. Frequency (IRFBC30), $R_{\rm tate}$ =22 $\Omega,\,V_{\rm CC}$ =15 V

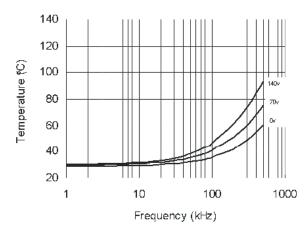


Figure 29. IRS2181 vs. Frequency (IRFBC40), $\rm R_{\rm gate}$ =15 $\Omega,\,\rm V_{\rm CC}$ =15 V

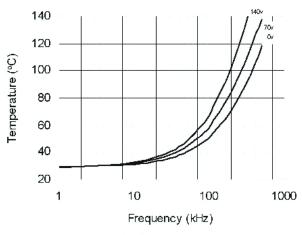


Figure 30. IRS2181 vs. Frequency (IRFPE50), $\rm R_{gate}$ =10 $\Omega,\,\rm V_{CC}$ =15 V

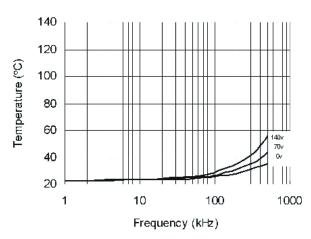


Figure 31. IRS21814 vs. Frequency (IRFBC20), ${\rm R_{oate}} {=} 33~\Omega, {\rm V_{cc}} {=} 15~{\rm V}$

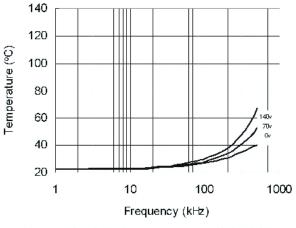


Figure 32. IRS21814 vs. Frequency (IRFBC30), ${\rm R_{oate}}\text{=}22~\Omega, {\rm V_{cc}}\text{=}15~{\rm V}$

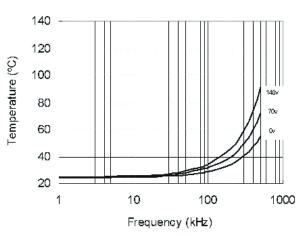


Figure 33. IRS21814 vs. Frequency (IRFBC40), $\rm R_{\rm gate}$ =15 Ω , $\rm V_{\rm cc}$ =15 V

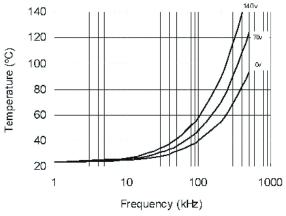


Figure 34. IRS21814 vs. Frequency (IRFPE50), $\rm R_{oute}$ =10 $\Omega,\,\rm V_{cc}$ =15 V

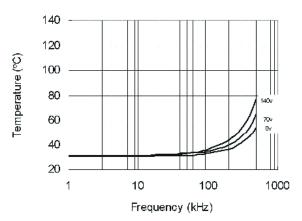


Figure 35. IRS2181s vs. Frequency (IRFBC20), $R_{\rm out}$ =33 Ω , $V_{\rm cc}$ =15 V

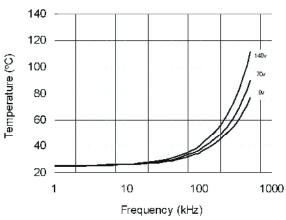


Figure 36. IRS2181s vs. Frequency (IRFBC30), $\rm R_{\rm gate}$ =22 Ω , $\rm V_{\rm CC}$ =15 V

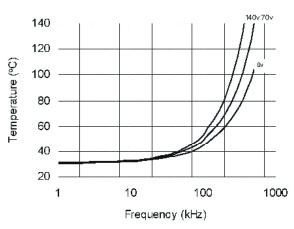


Figure 37. IRS2181s vs. Frequency (IRFBC40), $R_{\rm nate}$ =15 Ω , $V_{\rm CC}$ =15 V

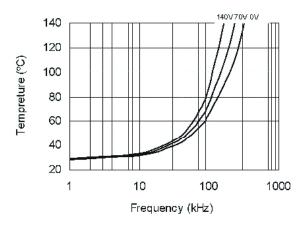


Figure 38. IRS2181s vs. Frequency (IRFPE50), $\rm R_{\rm gate}$ =10 $\Omega,\,\rm V_{\rm CC}$ =15 V

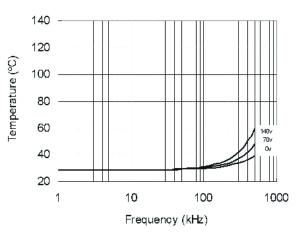


Figure 39. IRS21814s vs. Frequency (IRFBC20), $$\rm R_{oato}$=33~\Omega,\,V_{cc}$=15~V$

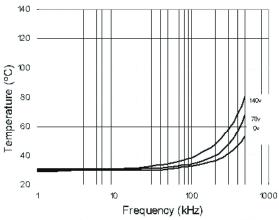


Figure 40. IRS21814s vs. Frequency (IRFBC30), ${\rm R_{oate}}{=}22~\Omega,~{\rm V_{CC}}{=}15~{\rm V}$

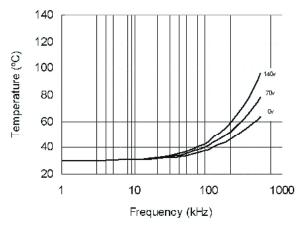


Figure 41. IRS21814s vs. Frequency (IRFBC40), $\rm R_{\rm gate}$ =15 Ω , $\rm V_{\rm CC}$ =15 V

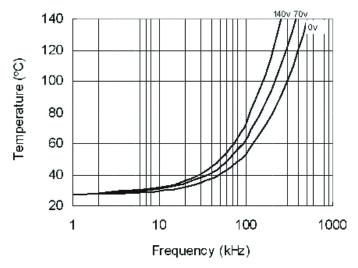
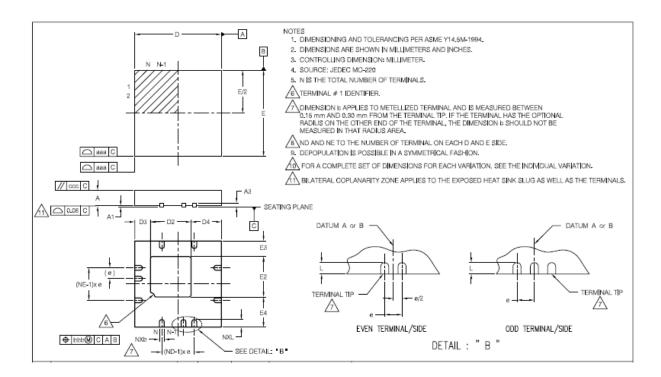


Figure 42. IRS21814s vs. Frequency (IRFPE50), $\rm R_{\rm gate}$ =10 Ω , $\rm V_{\rm cc}$ =15 V



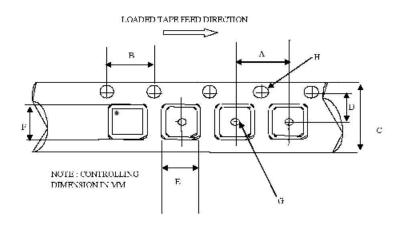
Package Details: MLPQ 4x4 -16L



SYM		VGGD-10				
M B O L	MILLIMETERS			INCHES		
Ľ	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	.032	-035	.039
A1	0.00	0.02	0.05	.000	-0008	.0019
А3		0.20 REF			.008 REF	
b	0.18	0.25	0.30	.007	.010	.012
D2	1.78	1.88	1.98	.070	.074	.078
D3	0.73 REF				.029 REF	
D4		1.40 REF	-		.055 REF	
D	4.00 BSC			.157 BSC		
Е		4.00 BS0		.157 BSC		
E4		1.40 REF		.055 REF		
E3		0.73 REF		.029 REF		
E2	1.78	1.88	1.98	.070	.074	.078
L	0.30	0.40	0.50	.012	.016	.020
е		0.50 PITC	H	.(20 PITC	1
N		16		16		
ND	4			4		
NE	4			4		
aaa	0.15			.0059		
bbb	0.10			.0039		
CCC		0.10		.0039		
ddd		0.05			.0019	

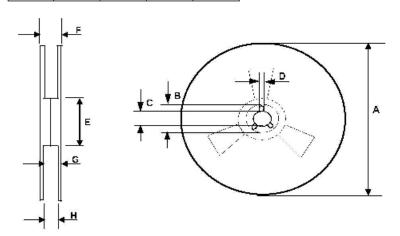


Tape and Reel Details: MLPQ 4x4



CARRIER TAPE DIMENSION FOR MLPQ4X4V

	Me	tric	Imperial		
Code	Min	Max	Min	Max	
A	7.90	8.10	0.311	0.358	
В	3.90	4.10	0.154	0.161	
C D	11.70	12.30	0.461	0.484	
D	5.45	5.55	0.215	0.219	
E.	4.25	4.45	0.168	0.176	
	4.25	4.45	0.168	0.176	
G	1.50	n/a	0.059	n/a	
H	1.50	1.60	0.059	0.063	

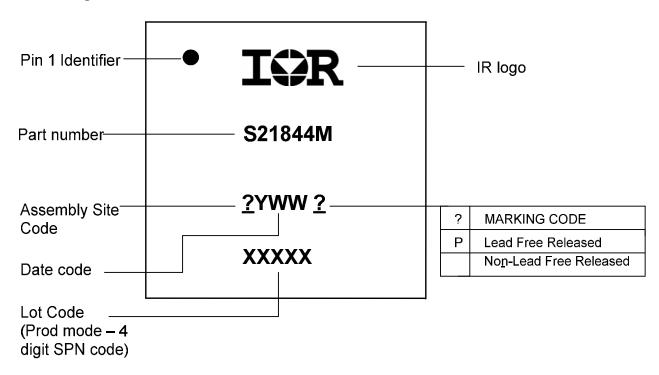


REEL DIMENSIONS FOR MLPQ4X4V

	Me	tric	Imperial		
Code	Min	Max	Min	Max	
A	329.60	330.25	12.976	13,001	
В	20.95	21.45	0.824	0.844	
С	12.80	13.20	0.503	0.519	
A B C D E	1.95	2.45	0.767	0.096	
E.	98.00	102.00	3.858	4.015	
F	n/a	18.40	n/a	0.724	
G H	14.50	17.10	0.570	0.673	
H	12.40	14.40	0.488	0.566	



Part Marking Information



Ordering Information

Daga Dawi Muwahay	Dooks as Time	Standard	Pack	Complete Dart Number	
Base Part Number	Package Type	Form	Quantity	Complete Part Number	
	MI DO 4 4 401	Tube/Bulk	92	IRS21844MPBF	
IRS21844	MLPQ 4x4-16L	Tape and Reel	3,000	IRS21844MTRPBF	

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For technical support, please contact IR's Technical Assistance Center http://www.irf.com/technical-info/

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Revision History

Date	Comment
09/24/09	Converted from existing data sheet; changing only package information
03/24/2010	Included Qual Info Page
08/09/2011	Update package info
02/06/2023	Add note regarding exposed pad